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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/838,520	04/19/2001	Geoffrey T. Haigh	A0312/7393 SJH	9453	
	90 05/28/2003				
WOLF GREENFIELD & SACKS, PC FEDERAL RESERVE PLAZA 600 ATLANTIC AVENUE			EXAMINER		
			DEBERADINIS, ROBERT L		
BOSTON, MA 02210-2211			ART UNIT	PAPER NUMBER	
		•	2836		
			DATE MAILED: 05/28/2003	DATE MAILED: 05/28/2003	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Application No. Applicant(s)					
•	Office Action Summary	09/838,520		GEOFFREY T. H	GEOFFREY T. HAIGH et al.			
	Office Action Summary	Examiner Robert L. DeBere	adinis	Art Unit 2836				
	The MAILING DATE of this communication appears	on the cover sheet wi	th the corre	spondence addre	ess			
	for Reply	=======================================	CONT					
THE	A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.							
- Extens	nsions of time may be available under the provisions of 37 CFR 1.136 (a). In ng date of this communication.				S from the			
- If the	period for reply specified above is less than thirty (30) days, a reply within the period for reply is specified above, the maximum statutory period will apply to	the statutory minimum of thirty	(30) days will b	e considered timely.				
- Failure	re to reply within the set or extended period for reply will, by statute, cause the reply received by the Office later than three months after the mailing date of the second sec	the application to become ABAN	NDONED (35 U.S	S.C. § 133).	nication.			
earned	d patent term adjustment. See 37 CFR 1.704(b).	this communication, even in turn	jely filed, may is	educe any				
Status 1) 🔀	•	222						
					·			
2a) ∐		tion is non-final.						
3) ∐	Since this application is in condition for allowance e closed in accordance with the practice under Ex particles.	except for formal mat	iters, prose	cution as to the	merits is			
Disposi	ition of Claims	Me Quayie, เฮออ ป.ป), 11; 405	0.G. 213.				
			is/are	e pendina in the	application.			
	4a) Of the above, claim(s)							
	Claim(s)							
	Claim(s) 14-23, 25, and 26							
_	Claim(s) 24 and 27				*=			
	Claims							
	ation Papers	are subject	il lu resure	TION BHU/OF SIGO	tion requirement.			
	The specification is objected to by the Examiner.							
10)💢	The drawing(s) filed on Feb 24, 2003 is/are	a) 💢 accepted or b)□ objecte	ed to by the Exa	miner.			
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
11)	The proposed drawing correction filed on							
	If approved, corrected drawings are required in reply t							
12)	The oath or declaration is objected to by the Examin	ner.						
_	under 35 U.S.C. §§ 119 and 120							
	5 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -							
	☐ All b)☐ Some* c)☐ None of:							
	1. Certified copies of the priority documents have							
	2. Certified copies of the priority documents have				<u> </u>			
	 Copies of the certified copies of the priority do application from the International Burea ee the attached detailed Office action for a list of the 	au (PCT Rule 17.2(a)).		this National St	age			
	Acknowledgement is made of a claim for domestic			-1				
a) 🗌	1			<i>3</i>].				
15) 🗌	Acknowledgement is made of a claim for domestic			and/or 121.				
Attachme	ent(s)		0. 22	uno, or				
		4) Interview Summary (PT	O-413) Paper N	io(s)				
2) Noti	tice of Draftsperson's Patent Drawing Review (PTO-948)	5) Notice of Informal Paten	nt Application (F	°TO-152)				

3) Information Disclosure Statement(s) (PTO-1449) Paper No(s).

6) Other:

5) Notice of Informal Patent Application (PTO-152)

Art Unit: 2836

DETAILED ACTION

1. In view of the appeal brief filed on 2/24/03, PROSECUTION IS HEREBY REOPENED.

New grounds for rejection set forth below.

To avoid abandonment of the application, appellant must exercise one of the following two options:

- (1) file a reply under 37 CFR 1.111 (if this Office action is non-final) or a reply under 37 CFR 1.113 (if this Office action is final); or,
 - (2) request reinstatement of the appeal.

If reinstatement of the appeal is requested, such request must be accompanied by a supplemental appeal brief, but no new amendments, affidavits (37 CFR 1.130, 1.131 or 1.132) or other evidence are permitted. See 37 CFR 1.193(b)(2).

Response to Amendment

After final amendment filed 2/24/03, entered.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person

Art Unit: 2836

having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

3. Claims 14-23, 25, 26 are rejected under 35 U.S.C. 103(a) as being unpatentable over IWASAKI 4,922,883 in view of DOUGLASS 5,786,979.

Regarding claims 14, 15, 25, 26.

IWASAKI discloses:

the first and second passive components being coils (figure 7, transformer 131); an input for receiving an input signal (figure 7, Sc); and

a driver circuit coupled between the input (figure 7, Sc) and one of said passive components (131, primary coil).

IWASAKI does not disclose:

- a first substrate;
- a first passive component formed on the first substrate;
- an isolation layer formed over the first passive component;
- a second passive component formed over the isolation layer;

DOUGLASS discloses high density inter-chip connecting by electromagnetic coupling (column 4, lines 21-25) comprising:

- a first substrate (abstract, line 7);
- a first passive component formed on the first substrate (abstract, capacitor plate); an isolation layer formed over the first passive component (column 4, line 55);

Art Unit: 2836

a second passive component formed over the isolation layer (column 4, line 55).

It would have been obvious to one having ordinary skill in the art at the time of this invention to provide a signal isolated comprising:

a first substrate;

a first passive component formed on the first substrate;

an isolation layer formed over the first passive component;

a second passive component formed over the isolation layer; and

a driver circuit coupled between the input and one of said passive components to provide inter-chip connections between circuits mounted on a substrate (column 4, lines 21-25).

Regarding claims 16, 17.

IWASAKI in view of DOUGLAS disclose the isolator of claim 14 or claim 15.

DOUGLAS discloses wherein the first substrate is a semiconductor substrate (column 1, lines 42-45, column 2, lines 47-67).

Regarding claim 18.

IWASAKI in view of DOUGLAS disclose the isolator of claim 16.

DOUGLAS discloses any chip may communicate with any other chip by propagating a transmitted signal from chip to chip (abstract).

Art Unit: 2836

Regarding claims 19, 20.

IWASAKI in view of DOUGLAS disclose the isolator of claim 16.

DOUGLAS discloses wherein the first passive component is formed on top of the first substrate (column 3, lines 17-50).

Regarding claims 21, 22, 23.

IWASAKI in view of DOUGLAS disclose the isolator of claim 16.

IWASAKI in view of DOUGLAS do not disclose the isolator further comprising a third passive component on the substrate, a second isolation layer over the third passive component, and a fourth passive component formed over the second isolation layer, wherein the driver circuit provides signals to the first and third passive components.

DOUGLAS discloses the first chip further includes a first means for coupling disposed over the substrate face and coupling underlying circuit (column 3, lines 16-32).

It would have been obvious to one having ordinary skill in the art at the time of tins invention to further include a third passive component on the substrate, a second isolation layer over the third passive component, and a fourth passive component formed over the second isolation layer, wherein the driver circuit provides signals to the first and third passive components to provide electromagnetic coupling between chips in high density multi chip substrate.

Page 5

77

Art Unit: 2836

Allowable Subject Matter

4. Claims 24, 27 are objected to as being dependent upon a rejected base claim, but would be

allowable if rewritten in independent form including all of the limitations of the base claim and any

intervening claims.

5. The following is a statement of reasons for the indication of allowable subject matter: the

prior art does not disclose or suggest to disclose Faraday shield referenced to the same ground as

the second passive components.

Any inquiry concerning this communication should be directed to Robert L. DeBeradinis

whose number is (703) 306-5857. The examiner can normally be reached on Monday-Friday from

8:30 am to 5:00 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Brian

Sircus, can be reached on (703) 308-3119. The fax phone number for this Group is (703) 308-

7722.

RLD

MAY 6, 2003 Rfef Ph Perh Page 6